<table>
<thead>
<tr>
<th>Layer</th>
<th>Name</th>
<th>Material</th>
<th>Thickness</th>
<th>Constant</th>
</tr>
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<tbody>
<tr>
<td>1</td>
<td>Top Overlay</td>
<td>Solder</td>
<td>0.4 mil</td>
<td>3.5</td>
</tr>
<tr>
<td>2</td>
<td>Top Layer</td>
<td>Copper</td>
<td>1.0 mil</td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>Substractive</td>
<td>FR-4</td>
<td>9.6 mil</td>
<td></td>
</tr>
<tr>
<td>4</td>
<td>Bottom Layer</td>
<td>Copper</td>
<td>1.4 mil</td>
<td></td>
</tr>
<tr>
<td>5</td>
<td>Bottom Solder</td>
<td>Solder Resist</td>
<td>0.4 mil</td>
<td>3.5</td>
</tr>
<tr>
<td>6</td>
<td>Bottom Overlay</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Design Information**

- **A**
  - NPL TRACK WIDTH: 8 mil
  - NPL CLEARANCE: 0.2 mm
  - NPL VIA PAD SIZE: 25 mil
- **B**
  - MINIMUM ANGULAR RING 0.030\(\text{mm}\) (0.01\(\text{in}\)) EXTERNAL
  - REGISTRATION TOLERANCE METAL +/- 5 mil, HOLES +/- 3 mil
- **C**
  - MATERIAL: FR-4 High Tg
  - THICKNESS: 0.02\(\text{in}\) (0.508\(\text{mm}\)) +/- 0.5% OTHER
  - SOLDER TYPE: ENIG 6000 TYPE 3 CLASS 2 OTHER
- **D**
  - DRILLING: AS SHOWN
  - PCB HEAT SINK THICKNESS: 0.030\(\text{in}\)
  - BOARD FINISH:
    - ENAMEL: Blue
    - SOLDER RESIST COLOR: ENAMEL
    - SURFACE FINISH: ENAMEL}

**Rev**

- 0.1

**Cut-out**

- 1000.00

**Scale**

- 1.00

**Dimensions**

- 14, 15, 42, 53
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